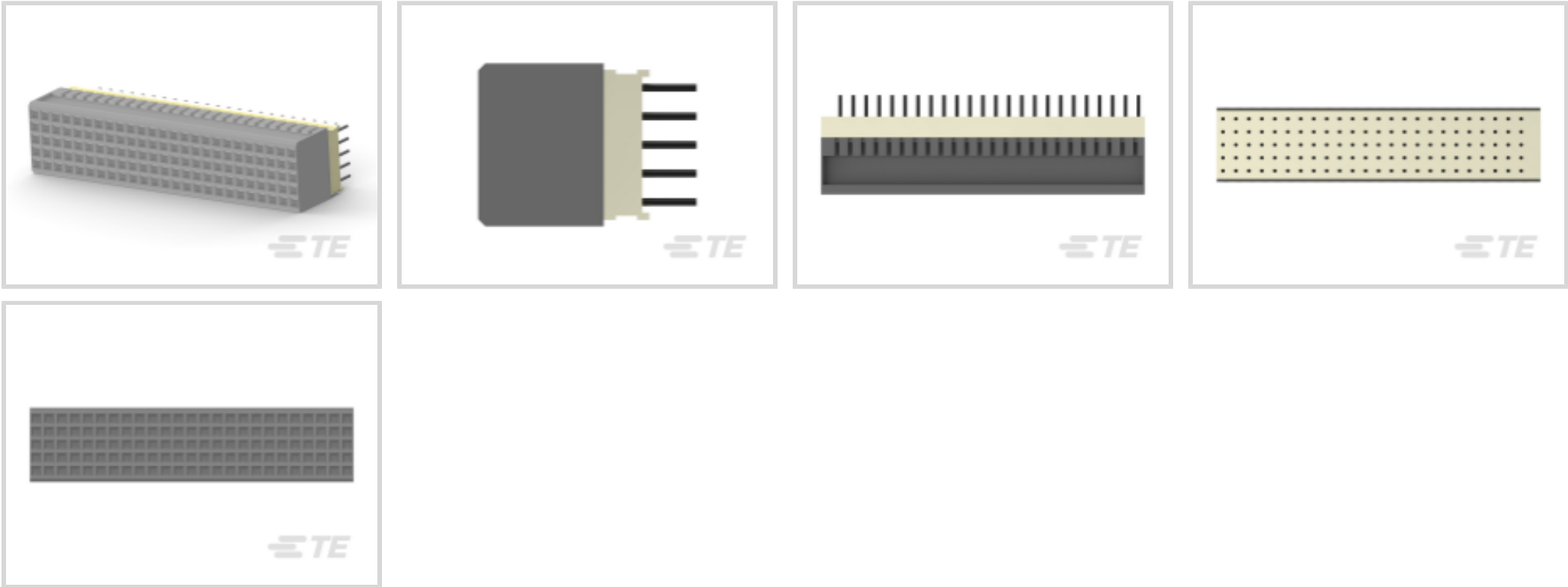




Connectors > PCB Connectors > Backplane Connectors > Hard Metric Connectors > Hard Metric Backplane Receptacle Connector: Mezzanine, 2mm



PCB Connector Assembly Type: **PCB Mount Receptacle**

Data Rate: **≤1 Gb/s**

Number of Columns: **25**

Number of Rows: **5**

Backplane Architecture: **Mezzanine**

[All Hard Metric Backplane Receptacle Connector: Mezzanine, 2mm \(27\)](#)

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Backplane Interface Type          | 2mm HM                |
| PCB Connector Assembly Type       | PCB Mount Receptacle  |
| Connector System                  | Board-to-Board        |
| Sealable                          | No                    |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

|                            |           |
|----------------------------|-----------|
| Number of Signal Positions | 110       |
| Number of Columns          | 25        |
| Number of Rows             | 5         |
| Backplane Architecture     | Mezzanine |
| Number of Positions        | 125       |
| PCB Mount Orientation      | Vertical  |



Signal Characteristics

|                   |         |
|-------------------|---------|
| Crosstalk Version | Reduced |
| Data Rate         | ≤1 Gb/s |

Contact Features

|                                                |                 |
|------------------------------------------------|-----------------|
| Contact Mating Area Length                     | 3.3 mm          |
| Feedthrough Post Length                        | 3.7 mm          |
| Contact Type                                   | Socket          |
| Contact Underplating Material                  | Nickel          |
| PCB Contact Termination Area Plating Material  | Tin             |
| Contact Base Material                          | Phosphor Bronze |
| CompactPCI Designation                         | None            |
| Contact Mating Area Plating Material           | Nickel          |
| Contact Mating Area Plating Material Thickness | 1.27 μm[50 μin] |
| Contact Current Rating (Max)                   | 1.5 A           |

Termination Features

|                                             |                          |
|---------------------------------------------|--------------------------|
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
|---------------------------------------------|--------------------------|

Mechanical Attachment

|                         |             |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

|                    |                |
|--------------------|----------------|
| Housing Material   | Polyester - GF |
| Centerline (Pitch) | 2 mm[.078 in]  |
| Housing Color      | Gray           |

Dimensions

|                         |       |
|-------------------------|-------|
| Backplane Module Length | 50 mm |
|-------------------------|-------|

Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 125 °C[-67 – 257 °F] |
|-----------------------------|----------------------------|

Operation/Application

|                     |                |
|---------------------|----------------|
| Shielded            | No             |
| Circuit Application | Power & Signal |

Industry Standards

|                               |          |
|-------------------------------|----------|
| UL Flammability Rating        | UL 94V-0 |
| AdvancedTCA Specified Product | No       |



Packaging Features

|                    |      |
|--------------------|------|
| Packaging Quantity | 11   |
| Packaging Method   | Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                       |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2022 (224)<br>Candidate List Declared Against: JUNE 2022 (224)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                  |
| Solder Process Capability                     | Not applicable for solder process capability                                                                                    |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 5100141-1  
2MM H.M. TYPE "B" PIN ASSY.



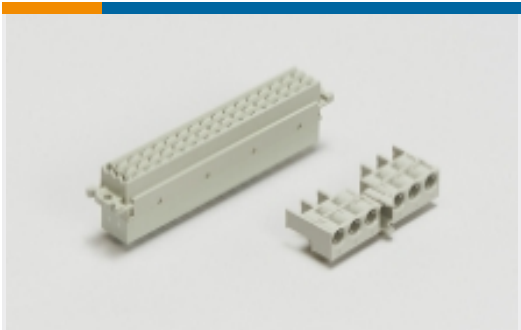
TE Part # 122561-1  
SUPPORT ANVIL 2MM H.M. 7 ROW

Also in the Series | Z-PACK 2mm HM





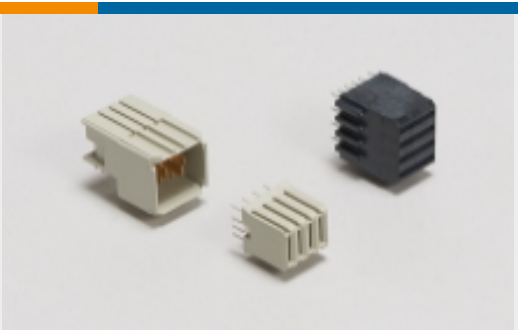
Backplane Coding Keys(60)



Backplane Connector Housings(4)



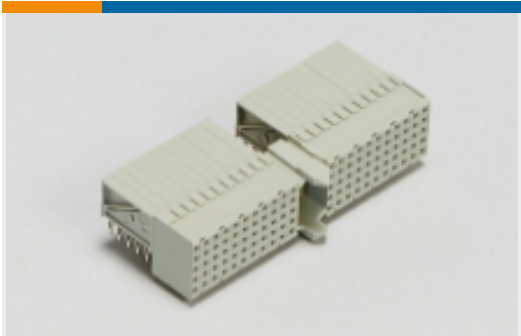
Backplane Guide Hardware(37)



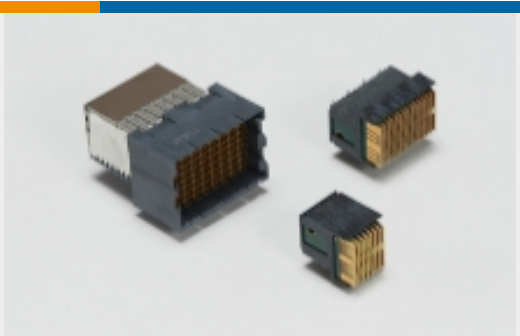
Backplane Power Connectors(6)



Board-to-Board Connector Contacts(2)



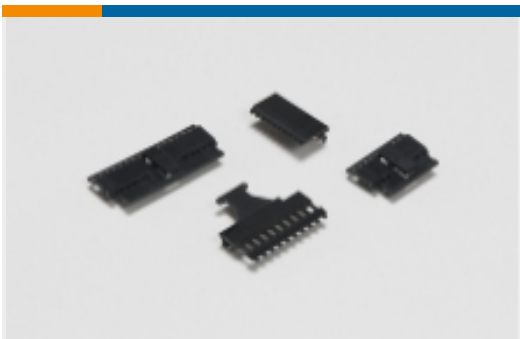
Hard Metric Backplane Connectors (269)



High Speed Backplane Connectors(1)



Insertion & Extraction Tools(2)



PCB Connector Covers(4)



PCB Connector Shrouds(39)



PCB Ferrules & Shields(19)



Rectangular Power Connectors(87)

Documents

Product Drawings

Z-PACK/B25 VF 125P

English

CAD Files

Customer View Model

ENG\_CVM\_CVM\_5106774-1\_A.2d\_dxf.zip

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_5106774-1\_A.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_5106774-1\_A.3d\_stp.zip

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

MD\_5106774-1\_051220141129\_dmtec

English

MD\_5106774-1\_051220141129\_dmtec

English